

Electronic Patent Application Fee Transmittal

Application Number:	10552046			
Filing Date:	09-Jan-2007			
Title of Invention:	MULTI-CHIP BALL GRID ARRAY PACKAGE AND METHOD OF MANUFACTURE			
First Named Inventor/Applicant Name:	Fung Leng Chen			
Filer:	Carl Joseph Pellegrini/Ingrid Contreras			
Attorney Docket Number:	Q74738			
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